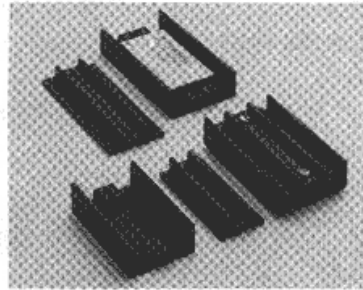


### FEATURES

- Supports hybrid and monolithic components
- Drastically decreases thermal resistance,  $\theta_{c-a}$
- Improves hybrid performance and reliability
- Anodized aluminum construction
- Low cost



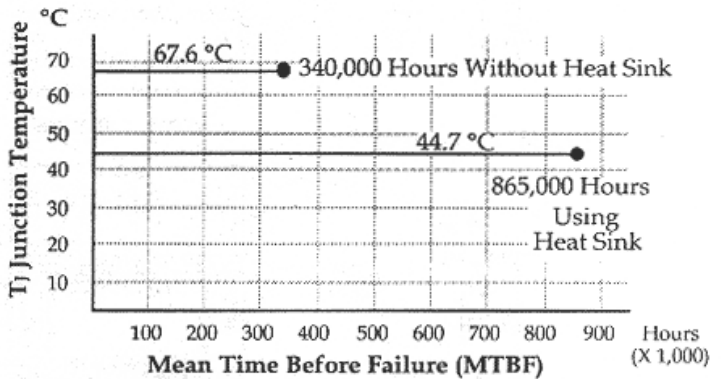
### GENERAL DESCRIPTION

To further increase both the electrical performance and reliability of hybrid components, DATEL offers aluminum heat sinks for conventional 24-pin DDIP, 32-pin TDIP, and 40-pin TDIP packages.

The HS Series of heat sinks is suitable for use with both side and bottom-brazed dual in-line packages. The heat sinks consist of a top and bottom part (cover and base) which enclose the package. A compressible, thermally-conductive silicone preform is used to seal the top and bottom components to the respective surfaces of the package, maximizing thermal contact. The HS-24, -32, and -40 heat sinks are designed for printed circuit board mounting.

The HS heat sinks are made of anodized aluminum which provides high levels of heat conduction and dissipation.

Performance improvements include a typical increase in MTBF of 250 percent and an average reduction in case temperature ( $T_c$ ) of 35 percent. This corresponds to an average decrease in junction temperature of 30 percent.



### SPECIFICATIONS

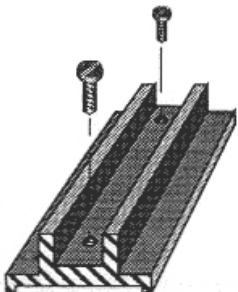
Package	$\theta_{c-a}$ (typ.)	Units
24-pin without HS-24	23	°C/W
24-pin with HS-24	9	°C/W
32-pin without HS-32	18	°C/W
32-pin with HS-32	7	°C/W
40-pin without HS-40	17	°C/W
40-pin with HS-40	6	°C/W

### ORDERING INFORMATION

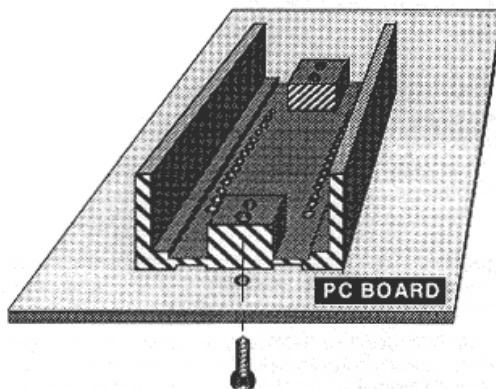
Part Number	Package Type
HS-24	24-pin DDIP
HS-32	32-pin TDIP
HS-40	40-pin TDIP

For additional information, request DATEL Application Note AN-8

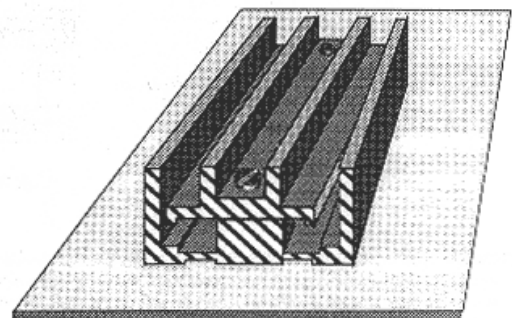
COVER



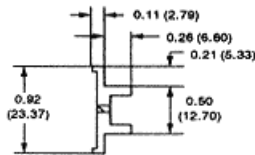
BASE



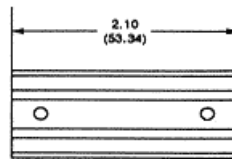
ASSEMBLED  
(DIP not Visible)



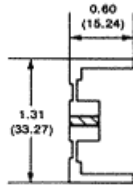
**MECHANICAL DIMENSIONS**  
Inches (mm)



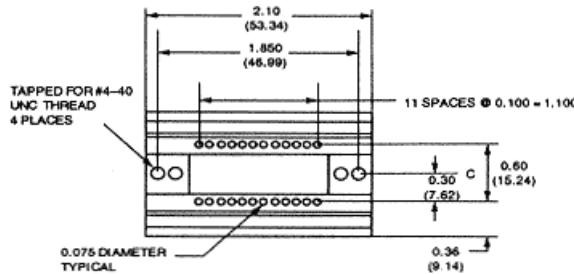
Cover, edge view



Cover, top view

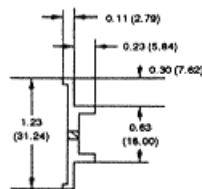


Base, edge view

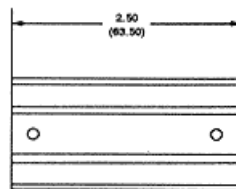


Base, top view

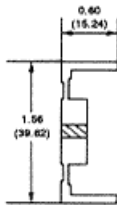
**Heat Sink for 24-Pin DDIP Packages**



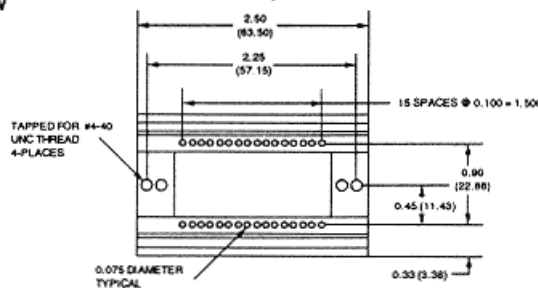
Cover, edge view



Cover, top view

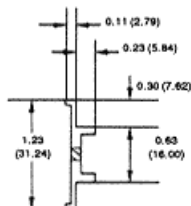


Base, edge view

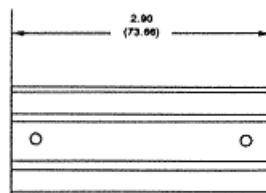


Base, top view

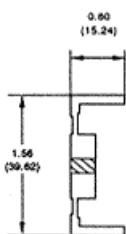
**Heat Sink for 32-Pin TDIP Packages**



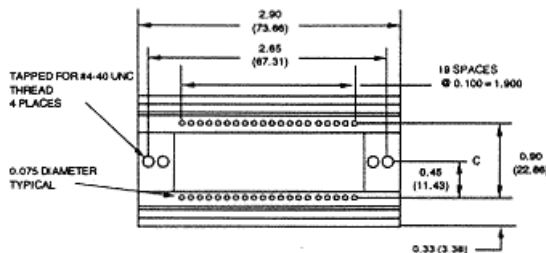
Cover, edge view



Cover, top view



Base, edge view



Base, top view

**Heat Sink for 40-Pin TDIP Packages**

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